



# Eurocircuits - Standard board build up 0-8 layers

**0 Layer STD Build 1.55mm 0.062"**

Core	1550µm	62mil
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**1 Layer STD Build 1.55mm 0.062"**

Core	1550µm	62mil
copper - 1	35µm	1oz

**2 Layer STD Build 1.55mm 0.062"**

copper - 1	18µm	½oz
Core	1550µm	62mil
copper - 2	18µm	½oz

**4 Layer STD Build 1.55mm 0.062"**

copper - 1	18µm	½oz
Prepreg 7628	180µm	7mil
Prepreg 7628	180µm	7mil
copper - 2	35µm	1oz
Core	710µm	27.95mil
copper - 3	35µm	1oz
Prepreg 7628	180µm	7mil
Prepreg 7628	180µm	7mil
copper - 4	18µm	½oz

**6 Layer STD Build 1.55mm 0.062"**

copper - 1	18µm	½oz
Prepreg 2125	100µm	4mil
Prepreg 2125	100µm	4mil
copper - 2	35µm	1oz
Core	360µm	14.2mil
copper - 3	35µm	1oz
Prepreg 7628	180µm	7mil
Prepreg 7628	180µm	7mil
copper - 4	35µm	1oz
Core	360µm	14.2mil
copper - 5	35µm	1oz
Prepreg 2125	100µm	4mil
Prepreg 2125	100µm	4mil
copper - 6	18µm	½oz

**8 Layer STD Build 1.55mm 0.062"**

copper - 1	18µm	½oz
Prepreg 2125	100µm	4mil
Prepreg 2125	100µm	4mil
copper - 2	35µm	1oz
Core	200µm	8mil
copper - 3	35µm	1oz
Prepreg 2125	100µm	4mil
Prepreg 2125	100µm	4mil
copper - 4	35µm	1oz
Core	200µm	8mil
copper - 5	35µm	1oz
Prepreg 2125	100µm	4mil
Prepreg 2125	100µm	4mil
copper - 6	35µm	1oz
Core	200µm	8mil
copper - 7	35µm	1oz
Prepreg 2125	100µm	4mil
Prepreg 2125	100µm	4mil
copper - 8	18µm	½oz

All materials are suitable for lead free soldering.  
We exclusively use FR-4 improved materials

The minima for the key material parameters are:  
**Td >= 325 °C**  
**T260 >= 60 min**  
**T288 >= 5 min**  
**CTEz <= 3.7%**  
**Tg >= 135°C**

All used materials comply with the RoHS regulations